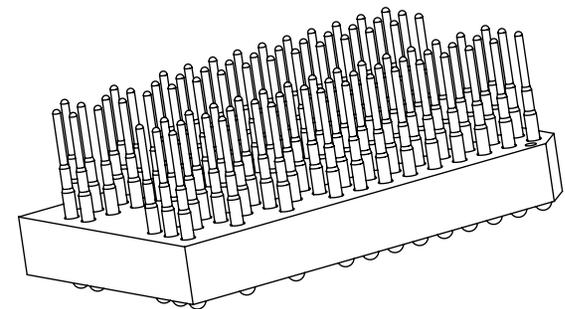
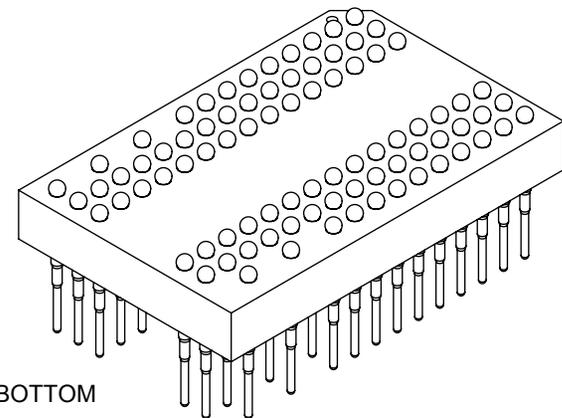


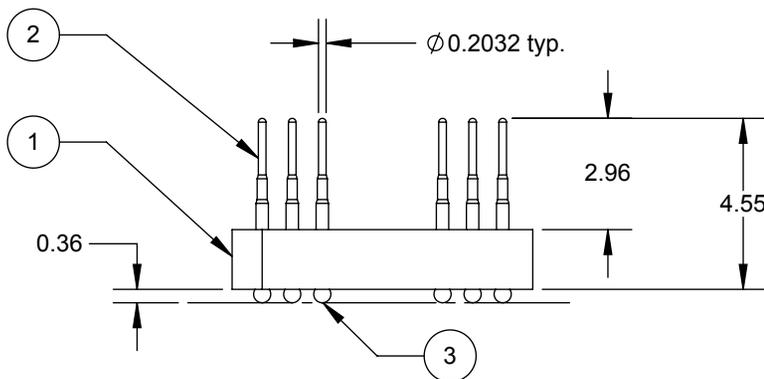
BOTTOM VIEW



ISO VIEW TOP



ISO VIEW BOTTOM



FRONT VIEW

- 1 Substrate: 1.59±0.18mm [0.0625"±0.007"] non clad high temp material.
- 2 Pins: material-Brass Alloy 360 1/2 hard; finish- 0.25µm [10µ] Au over 1.27µm [50µ"] Ni (min)
- 3 Solder Balls: Sn96.5Ag3.0Cu0.5

Description: Giga-snaP BGA SMT ball on pin land socket for 8mm x12.5mm 84 pin 0.8mm pitch BGA

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

Tolerances: Hole diameters ±0.0254mm [±0.001"]. Pitches (from true position) ±0.0762mm [±0.003"], substrate thickness tolerance ±10%, all other tolerances ±0.127mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

Doc Rev	Date	Initials	Description
A	9/30/15	SF	Original

 SF-BGA84H-B-61F Drawing Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	Material: N/A Finish: N/A Weight: 0.48	STATUS: Released ENG: S. Faiz FILE: SF-BGA84H-B-61F Dwg	SHEET: 1 OF 1 DRAWN BY: S. Faiz DATE: 9/30/15	REV. A SCALE: 5:1